

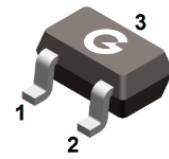
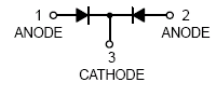
Features

- High speed switching
- High reliability

HF

Mechanical Data

- Case: SOT-323
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



SOT-323

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
DAN202U	SOT-323	3000 pcs / Tape & Reel	N

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V _{RM}	80	V
Reverse Voltage	V _R	80	V
Average Rectified Output Current	I _F	100	mA
Forward Continuous Current (Peak)	I _{FM}	300	mA
Peak Forward Surge Current, (t = 1μs)	I _{FSM}	4	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	200	mW
Thermal Resistance Junction-to-Air ^{*1}	R _{θJA}	466	°C/W
Thermal Resistance Junction-to-Case ^{*1}	R _{θJC}	250	°C/W
Thermal Resistance Junction-to-Lead ^{*1}	R _{θJL}	271	°C/W
Operating Junction Temperature Range	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Note 1: The data tested by surface mounted on a 15mm * 15mm * 1mm FR4-epoxy P.C.B

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R = 100\mu\text{A}$	80	-	-	V
Forward Voltage	V_F	$I_F = 100\text{mA}$	-	-	1.2	V
Maximum Peak Reverse Current	I_R	$V_R = 70\text{V}$	-	-	0.1	μA
Total Capacitance	C_J	$V_R = 6\text{V}, f = 1.0\text{MHz}$	-	-	3.5	pF
Reverse Recovery Time	t_{rr}	$I_F = 5\text{mA}, V_R = 6\text{V}$ $R_L = 50\Omega$	-	-	4	ns

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

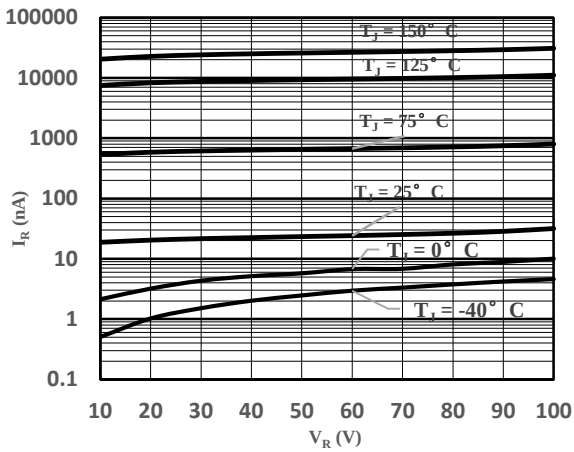


Fig 1 Typical Reverse Characteristic

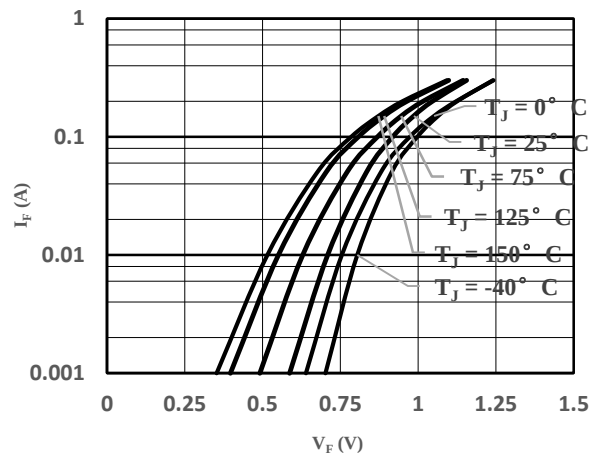


Fig 2 Typical Forward Characteristics

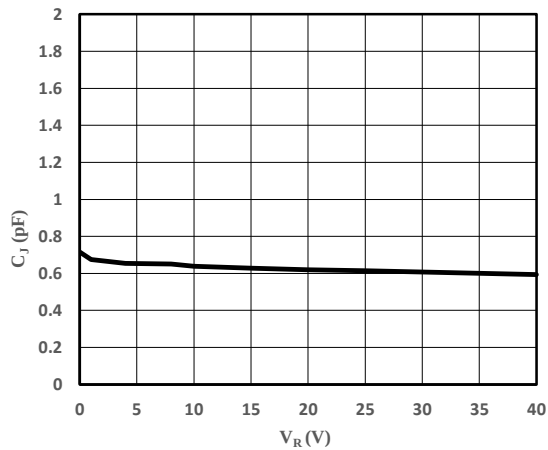
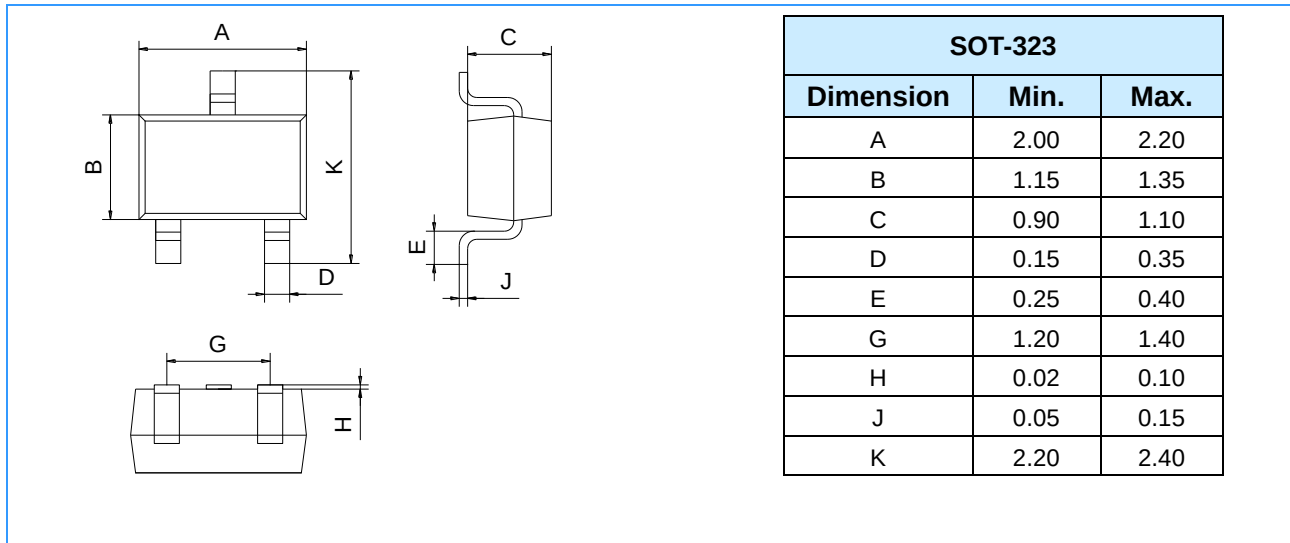
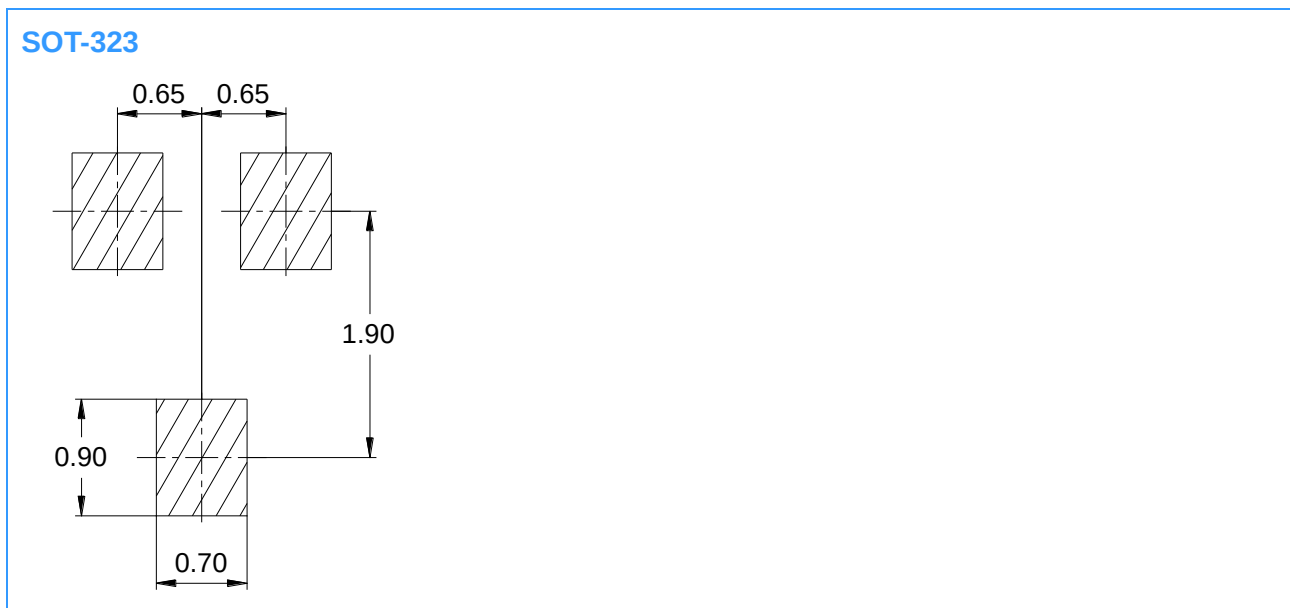


Fig 3 Capacitance vs. Reverse Voltage

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)



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